(Rev. U3-U1)	9 - 2002 U.S. DEPARTMENT OF COMMERC
POB/REV03	
To the Honorable Commissioner of Patents pure requirements.	DESCRIPTION AND AMACHED original documents or copy thereof.
1. Name of conveying party(ies): Kazuhiko Ohashi Osamu Yokomizo Keji Yoshida	2. Name and address of receiving party(les):
Koji Yoshida	Name: JAPAN GORE-TEX, INC.
9.251022	Internal Address:
Additional names(s) of conveying party(ies)	
3. Nature of conveyance:	
☑ Assignment ☐ Merger	Street Address: 42-5, 1-Chome, Akazutsumi
☐ Security Agreement ☐ Change of Name	Setagaua=Li
☐ Other	City: Tokyo 156, JAPAN State: ZIP:
Execution Date: September 18, 2002	Additional name(s) & address(es) attached? Yes No
Application number(s) or patent numbers(s):	
If this document is being filed together with a new application,	the execution date of the application is:
A. Patent Application No.(s)	B. Patent No.(s)
A. Laterit Application No.(3)	D. Faterit NO.(3)
10/175,141 June 19, 2002	
Additional numbers attac	│ hed? ❑ Yes ⊠ No
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Allan Wheatcraft	7. Total fee (37 CFR 3.41):\$ 40.00
Internal Address: W. L. Gore & Assaociates, Inc.	
	 Enclosed - Any excess or insufficiency should be credited or debited to deposit account
	Authorized to be charged to deposit account
Street Address: 551 Paper Mill Road	8. Deposit account number:
10/02/2002 DBYRNE 00000051 071729 10175141	07-1729
01 FC:581 40.00 CH City: Newark State: DE ZP: 19711	(Attach duplicate copy of this page if paying by deposit account)
	USE THIS SPACE
 Statement and signature. To the best of my knowledge and belief, the foregoing information of the original document. 	ation is true and correct and any attached copy is a true copy
Allan M. Wheatcraft	September 20, 2002
Name of Person Signing	Signature Date
Total number of pages including cover sh	neet, attachments, and document:

Mail documents to be recorded with required cover sheet information to:

P.02/03

Attorney Docket No.: WC/472

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<u>ASSIGNMENT</u>

WHEREAS, We, Ohashi Kazuhiko, Osamu Yokomizo and Koji Yoshida, as assignors have made an invention entitled, Integrated Circuit Chip Bonding Sheet and Integrated Circuit Package, for which We have signed papers for application of U.S. Letters Patent on June 19, 2002 (U.S. Patent Application Serial Number 10/175,141), and whereas JAPAN GORE-TEX, INC., of Tokyo, Japan, whose address is 42-5, 1-Chome, Akazutsumi, Setagaya-Ku, Tokyo 156, Japan, as assignee, is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW, THEREFORE, be it known that for good and valuable consideration the receipt of which from assignee is hereby acknowledged. We as assignors, have sold, assigned. transferred, and set over, and do hereby sell, assign, our entire rights, titles, and interests in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and We hereby authorize and request the Commissioner of Patents of the United States and any official of any foreign country whose duty it is to issue Patents on applications as described above, to issue all Letters Patent for this invention to assignee. Its successors and assigns, in accordance with the terms of this Agreement;

AND. We hereby covenant that We have the full right to convey the interest assigned by this Assignment, and We have not executed and will not execute any agreement in conflict with this Assignment;

AND, We hereby further covenant and agree that We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called up to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in sald assignee, its successors and assigns, execute all divisional, continuation. and reissue application, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

> PATENT REEL: 013338 FRAME: 0251

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IN TESTIMONY WHEREOF, I have hereunto set my hand this $\frac{1}{\delta}$ day of September, 2002.

Kazuhiki Ohashi

IN TESTIMONY WHEREOF, I have hereunto set my hand this 18 day of September, 2002.

Osamu Yokomizo

IN TESTIMONY WHEREOF, I have hereunto set my hand this $\frac{18}{100}$ day of September, 2002.

Koji Jskida Koji Yoshida

** TOTAL PAGE.03 **

PATENT REEL: 013338 FRAME: 0252